

**Remarks**

In view of the above amendments and the following remarks, reconsideration and further examination are requested.

A number of editorial amendments have been made to the specification. One of the amendments updates the continuation information as required in the Office Action. It is submitted that no new matter has been added to the application via such amendments. As a result, withdrawal of the objection to the specification is respectfully requested.

Further, claims 1-10, 13 and 14 have been amended to make a number of editorial revisions. These revisions have been made to place the claims in better U.S. form. None of these amendments have been made to narrow the scope of protection of the claims, nor to address issues related to patentability and therefore, these amendments should not be construed as limiting the scope of equivalents of the claimed features offered by the Doctrine of Equivalents.

Claims 1, 3, 5, 7 and 13 have been rejected under 35 U.S.C. §102(b) as being anticipated by Miyamoto (WO 97/40494). Claims 2, 4, 6, 8, 10, 12 and 14 have been rejected under 35 U.S.C. §103(a) as being unpatentable over Miyamoto in view of Kanashima (WO 97/35720). Claims 9 and 11 have been rejected under 35 U.S.C. §103(a) as being unpatentable over Miyamoto.

Claims 1 and 2 have been amended so as to further distinguish the present invention from the references relied upon in the rejections. As a result, the rejections are submitted to no longer be applicable for the following reasons.

Claim 1 is patentable over Miyamoto, since claim 1 recites a method including, in part, detecting that radiation cure resin has been diffused towards first and second central bores of integral first and second substrates, respectively, and irradiating, after the detecting, radiation to a whole of at least one opposite outer face of the integral first and second substrates so as to cure the radiation cure resin wholly. Miyamoto fails to disclose or suggest these features of claim 1.

Miyamoto discloses an apparatus for manufacturing optical discs. During the manufacturing process, a number of work parameters are initialized to specific parameters (S100). In response to a correction signal Sc, which is a feedback signal, the work parameters are updated, if necessary (S200). A first substrate 6 is then rotated a

specific number of times at a specific low speed and resin PP is applied to the first substrate 6 (S300). The first substrate 6 and a second substrate 9 are then superimposed (S400).

The superimposed substrates 6 and 9 are spun at a high speed to spread the resin PP while suctioning the resin PP from an inner circumference side (S500). Next, ultraviolet rays are irradiated to the substrates 6 and 9 to provisionally secure the substrates 6 and 9 (S600). The provisionally secured substrates 6 and 9 are then irradiated further with ultraviolet rays to harden the resin PP and fix the substrates 6 and 9 into an optical disc recording medium OD (S700). A laser focus displacement sensor is then used to measure a thickness Da of the adhesive layer AS (the cured resin PP) and it is determined whether or not the thickness Da is within a tolerance range (S800 and S900). (See column 9, line 23 – column 10, line 61 and Figures 1 and 2).

Based on the above discussion, it is apparent that the manufacturing method of Miyamoto cures the resin PP in steps S600 and S700 before measuring the thickness Da of the adhesive layer AS to determine if the adhesive layer AS is within a tolerance range in steps S800 and S900. On the other hand, claim 1 recites that the radiation is irradiated to the whole of the at least one opposite outer face of the integral first and second substrates after the detection that the radiation cure resin has been diffused towards the first and second central bores of the integral first and second substrates. Therefore, it is apparent that Miyamoto fails to disclose or suggest the present invention as recited in claim 1.

As for Kanashima, it is relied upon as disclosing an adhesive injector 30 having an injection nozzle 32. However, Kanashima fails to disclose or suggest the above-discussed features of claim 1.

As for claim 2, it is patentable over the references for the same reasons discussed above in support of claim 1. That is, claim 2 recites a method including, in part, detecting that radiation cure resin has been diffused towards first and second central bores of integral first and second substrates, respectively, and irradiating, after the detecting, radiation to a whole of at least one opposite outer face of the integral first and second substrates so as to cure the radiation cure resin wholly, which features are not disclosed or suggested by the references.

Because of the above-mentioned distinctions, it is believed clear that claims 1-14 are allowable over the references relied upon in the rejections. Furthermore, it is submitted that the distinctions are such that a person having ordinary skill in the art at the time of invention would not have been motivated to make any combination of the references of record in such a manner as to result in, or otherwise render obvious, the present invention as recited in claims 1-14. Therefore, it is submitted that claims 1-14 are clearly allowable over the prior art of record.

In view of the above amendments and remarks, it is submitted that the present application is now in condition for allowance. The Examiner is invited to contact the undersigned by telephone if it is felt that there are issues remaining which must be resolved before allowance of the application.

Respectfully submitted,

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